ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® International and Pan	C, Bannockb	ourn, Illinois. A	Il rights reserved u ntions.	nder both	This docum level parts, t	ent is a declarati the declaration e	on of the su ncompasses	bstances all lowe	within the manufactu r level materials for w	rer listed	item. Note: i manufacturer	f the item is an as r has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg I					Afg Informat	ion			
Supplier Information														
Company name* Comp			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2025-07-04			
Contact Name Title - Contact			ct	I			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repres			resentative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product Enviro			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		mber Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type	
	MBRS36	50T3G	REC SMC 3A 60V SHTKY TR			2025-07-04		1	VN5		252.0	mg	Each	
Manufacturing Proccess Informat	ion							<u> </u>						
Terminal Plating / Grid Array Ma	Terminal Plating / Grid Array Material Terminal Base A		Alloy J	-STD-020 MSL	L Rating	Peak Proc	ess Body Te	emperatur	re Max Time at Peak	Tempera	ture Numb	per of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy		1	1		260		С	30	seco	nds 3				
Comments														
level 1 - maximum time at peak temperatu	re during sol	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
lease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part normalies a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall normaps all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, s of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not idependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in the sole and exclusivesource of the Supplier remote of the Supplier fuely contributions of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the 'arranty rights and/or remedies of Supplier's Standard Terms andConditions of S										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	39.16	mg	Supplier	Iron (Fe)	7439-89-6		0.0392	mg
			Supplier	Copper (Cu)	7440-50-8		39.1091	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0117	mg
Die	2.91	mg	Supplier	Silicon (Si)	7440-21-3		2.91	mg
Die Attach Solder	2.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0705	mg
			А	Lead (Pb)	7439-92-1	7a	2.6085	mg
			Supplier	Tin (Sn)	7440-31-5		0.141	mg
Lead Frame	74.95	mg	Supplier	Iron (Fe)	7439-89-6		0.075	mg
			Supplier	Copper (Cu)	7440-50-8		74.8526	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0225	mg
Mold Compound-Black	131.5	mg	Supplier	Polycondensate of 4,4'- bis(methoxymethyl)biphenyl and phenol	205830-20-2		3.2875	mg
			Supplier	Triphenylphosphine	603-35-0		0.6575	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.6575	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.6575	mg
			Supplier	Carbon Black (C)	1333-86-4		1.315	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		118.35	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		6.575	mg
Plating	0.66	mg	Supplier	Tin (Sn)	7440-31-5		0.66	mg